

## **LISTING OF THE CLAIMS**

This listing of claims replaces all prior versions and listings of claims in the application:

**1. - 6. (Canceled)**

**7. (Currently Amended)** A substrate processing method comprising:

a first step of supplying an alkaline solution to a surface of a substrate;

a second step of supplying an acid solution to the surface of said substrate after said first step; and

a third step of supplying said alkaline solution to the surface of said substrate after said second step, ~~wherein~~

rotating said substrate in a horizontal plane from said first step to said third step; and

said supplying of said alkaline solution in said first step and said third step comprises injection and collision of droplets formed by mixing said alkaline solution with gas to the surface of the rotated substrate, and

wherein said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water,

said acid solution supplied in said second step is an acid solution having an etching effect,  
and

said alkaline solution and said acid solution are both solutions at ordinary temperature.

**8. (Currently Amended)** The substrate processing method according to claim 7, wherein only the supplying ~~supply~~ of said alkaline solution in said first step and said third step is injection of droplets formed by mixing said alkaline solution with gas.

**9. (Canceled)**

**10. (Previously Presented)** The substrate processing method according to claim 8, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

**11. (Currently Amended)** A substrate processing method comprising:  
a first step of supplying an alkaline solution to a surface of a substrate;  
a second step of supplying an acid solution to the surface of said substrate after said first step; and  
a third step of supplying said alkaline solution to the surface of said substrate after said second step, ~~wherein~~  
rotating said substrate in a horizontal plane from said first step to said third step, and  
the supplying of said alkaline solution in said first step and said third step comprises supplying of said alkaline solution subjected to megasonic vibrations to the surface of the rotated substrate, and  
wherein said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water,  
said acid solution supplied in said second step is an acid solution having an etching effect,  
and  
said alkaline solution and said acid solution are both solutions at ordinary temperature.

**12. (Currently Amended)** The substrate processing method according to claim 11, wherein only the ~~supplying~~ ~~supply~~ of said alkaline solution in said first step and said third step is performed with said alkaline solution subjected to megasonic vibrations.

**13. (Canceled)**

**14. (Previously Presented)** The substrate processing method according to claim 12, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

**15. - 20. (Canceled)**

**21. (Previously Presented)** The substrate processing method according to claim 7, said alkaline solution and said acid solution being at an ordinary temperature.

**22. (Previously Presented)** The substrate processing method according to claim 21, wherein said alkaline solution has a pH value of at least 11 and less than 13.

**23. (Previously Presented)** The substrate processing method according to claim 11, said alkaline solution and said acid solution being at an ordinary temperature.

**24. (Previously Presented)** The substrate processing method according to claim 23, wherein said alkaline solution has a pH value of at least 11 and less than 13.

**25. - 26. (Canceled)**

**27. (Previously Presented)** The substrate processing method according to claim 7, wherein droplets of said alkaline solution are injected from a nozzle to said surface of said substrate in said first step.

**28. (Previously Presented)** The substrate processing method according to claim 11, wherein said alkaline solution is discharged from a nozzle to said surface of said substrate in said first step.

**29. (Currently Amended)** A substrate processing method comprising:  
a first step of supplying an alkaline solution to a surface of a substrate;  
a second step of supplying an acid solution to the surface of said substrate after said first step; and  
a third step of supplying said alkaline solution to the surface of said substrate after said second step, ~~wherein~~  
rotating said substrate in a horizontal plane from said first step to said third step, and

the supplying supply of said acid solution in said second step comprises injection and collision of droplets formed by mixing said acid solution with gas to the surface of the rotated substrate, and

wherein said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water,

said acid solution supplied in said second step is an acid solution having an etching effect, and

said alkaline solution and said acid solution are both solutions at ordinary temperature.

**30. (Currently Amended)** A substrate processing method comprising:

a first step of supplying an alkaline solution to a surface of a substrate;

a second step of supplying an acid solution to the surface of said substrate after said first step; and

a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein

rotating said substrate in a horizontal plane from said first step to said third step, and

the supplying supply of said acid solution in said second step comprises supplying of said acid solution subjected to megasonic vibrations to the surface of the rotated substrate, and

wherein said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water,

said acid solution supplied in said second step is an acid solution having an etching effect, and

said alkaline solution and said acid solution are both solutions at ordinary temperature.